

MECHANIC Unique Solder Paste
(Instructions for use)

1. Product Name: MECHANIC Unique Solder Paste

型号 Model No.	XG30 (出口)(Export)	XGSP 30	XG40 (出口)(Export)	XGSP 40	XG50 (出口)(Export)	XGSP 50	XG-Z40	XGSP 80	XGSP 200	XGSP 500
重量 Weight	16G	20G	30G	35G	35G	42G	35G	60G	200G	500G

2. Product Composition: the product mainly adopts tin, lead alloy, melting point at 183 °C.

3. Product Performance: Solder paste is a new type of soldering material that came into being along with SMT, it is a paste mixture formed by mixing solder powder, flux and other surfactants, thixotropic agents and so on. Mainly used in SMT industry PCB surface resistance, capacitance, IC and other electronic components welding.

4. Features:

- 1、 Leaded solder paste has excellent soldering performance, can be in different parts of the performance of the appropriate wettability;
- 2、 Leaded solder paste can be adapted to the requirements of different grades of welding equipment, without the need to complete the welding in a nitrogen-filled environment, in a wide range of reflow oven temperature within the model can still show good welding performance, with the warming-insulation type or gradual heating type of two types of furnace temperature setting can be used;
- 3、 Leaded solder paste soldering residue is very little, the color is very light and has a large insulation resistance, will not corrode the PCB, can achieve the requirements of the no-wash;
- 4、 Leaded solder paste has a better ICT test performance, will not produce a false judgment.
- 5、 Leaded solder paste can be used for through-hole roller coating.

5. Usage:

Stir the solder paste well before use. It takes about 5 minutes in the automatic mixer.

3. The time to open the lid of the solder paste should be short, when enough solder paste is taken out, the inner lid of the solder paste should be closed immediately. In the use of, do not take a little with a little in the process, try to avoid frequent use of the lid or a long time will be completely open the lid of the solder paste box.

4. After removing the solder paste, close the lid immediately.

5. Removed solder paste should be used within a short period of time. The use of the process should be continuous work, has been all the use of solder paste clean, flat on the workbench waiting to be placed on the table components. Do not use the process of intermittent.

6. For has been taken out for the processing of solder paste, after the completion of the work of the shift, the rest of the solder paste should be immediately recycled to an empty bottle, the preservation process should pay attention to the air and completely isolated from the preservation.

7. Never put the remaining solder paste into the bottle of unused solder paste. Therefore, we should try to accurately deal with the problems in the process of taking solder paste. If there has been a solder paste surface crusting, hardening, never stir! Be sure to get rid of the hard skin, hard pieces, the remaining solder paste in the official use of the test to see how the trial effect, if not, it can only be scrapped!

6. Precautions:

1. Before using solder paste to wear good gloves, masks and other protective clothing.

2. Wash thoroughly after use.